Curriculum Structure of Advanced Semiconductor Packaging and Testing【International Program】
(Applicable to students enrolling in September, 2026)

Grade	Courses
Grade 1	**Students must take 4 courses each semester in the first year** ● Structural Design and Process of Electronic Packaging Technology* ● Applied Mechanics and Mechanics of Materials* ● Materials Science* ● Advanced Polymer-Based Electronic Packaging Materials* ● Semiconductor Wafer Bonding Technology and Application* ● Semiconductor Reliability Engineering* ● Application of Laser Micro-Micromachining in Electronic Packaging* ● Advanced Semiconductor Lithography Technology* ● Introduction of Wide Band Gap Compound Semiconductor Technology* ● Surface Characterization of Materials* ● Special Issues in Material Design* ● Computer Aided Engineering Analyses and Design* ● Special Issues in Functional Polymer Materials* ● Sensor Theory and Assembly Packaging Technology Application* ● Advanced Packaging Process and Heterogeneous Integration Packaging Technology*
Grade 2	Master's Thesis Research

Note: * Indicates English-taught courses.

Eligibility requirements for Master's degree examination:

At least 24 credits, limited to English-taught courses offered by the Advanced Semiconductor Packaging and Testing Institute, should be completed.

Curriculum Structure of Advanced Semiconductor Packaging and Testing 【Domestic Students】
(Applicable to students enrolling in September, 2026)

<table>
<tr><th>Grade</th><th>Semester</th><th>Compulsory Courses</th><th>Elective Courses</th></tr>
<tr><td rowspan="2">Grade 1</td><td>1st Semester</td><td>Minimum: 1 course
● Semiconductor Packaging Engineering
● Structural Design and Process of Advanced Electronic Packaging Technology*</td><td rowspan="2">Minimum: 3 courses in the 1st semester and 1 course in the 2nd semester.
● Semiconductor Reliability Engineering*
● Applied Mechanics and Mechanics of Materials*
● Advanced Polymer-Based Electronic Packaging Materials*
● Semiconductor Wafer Bonding Technology and Application*
● Advanced Semiconductor Lithography Technology*
● Application of Laser Micro-Micromachining in Electronic Packaging*
● Intelligent Manufacturing and Control Practices
● System-Level Static Electricity and Electromagnetic Interference
● Materials Science*
● Polymer Materials
● Product Analysis
● Optoelectronics and Devices
● Microwave Circuit and System
● Sensor Theory and Assembly Packaging Technology Application*
● Special Issues in Material Design*
● Surface Characterization of Materials*
● Computer Aided Engineering Analyses and Design*
● Introduction of Wide Band Gap Compound Semiconductor Technology*
● Image Recognition
● Introduction of Semiconductor Engineering Technology
● Advanced packaging process and heterogeneous Integration Packaging Technology*
● Special Issues in Functional Polymer Materials*
● Organic Semiconductor Materials and Devices
● Engineering Statistics and Quality Management
● Design and Testing For System Circuit
● High-speed And High Frequency Circuit Simulation and Measurement</td></tr>
<tr><td>2nd Semester</td><td>● Experiment on Semiconductor Packaging Processes</td></tr>
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Note: * Indicates English-taught courses.

Grade	Semester	Compulsory Courses
Grade 2	1st Semester	● Special Topics & Technical Reports in Advanced Semiconductor Packaging and Testing (I)
	2nd Semester	● Special Topics & Technical Reports in Advanced Semiconductor Packaging and Testing (II)
Grade 3	1st Semester	● Special Topics & Technical Reports in Advanced Semiconductor Packaging and Testing (III)

Program	Grade	Semester	27 Credits of Compulsory Internship Courses for Grad 1 to 3 Students
Internship in the Institute of Advanced Semiconductor Packaging and Testing	Grade 1	2nd Semester	● Internship in Basic Introduction to Semiconductor ● Internship in Manufacturing of Semiconductor Assembly and Testing
	Grade 2	1st Semester	● Introduction to Statistical Process Control ● Professional Courses and Applications (Level 1)–Professional Teaching
		2nd Semester	● Application of Quality Management Core Tools ● Professional Courses and Applications (Level 2)–Project Planning and Execution
		Summer Semester	● High-End Electronic Product Practice
	Grade 3	1st Semester	● Project Reporting - Acceptance and Planning (A) ● Project Reporting - Acceptance and Planning (B)